



Attorney Docket No. 5649-905

#4/A 2825  
D/King  
8-5-03

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Hong-Sik Jeong et al.

Serial No.: 10/008,700

Filed: December 7, 2001

For: METHODS OF MANUFACTURING INTEGRATED CIRCUIT DEVICES  
HAVING AN ENCAPSULATED INSULATION LAYER

Confirmation No.: 5150

Group Art Unit: 2825

Examiner: Chuong A. Luu

Date: July 22, 2003

Mail Stop Non-Fee Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

Applicant provides the present Amendment to address the issues raised in the Official Action mailed April 24, 2003 ("the Action"). The present amendment is provided in the Revised Amendment Format as published in the Official Gazette on February 25, 2003. The Revised Amendment Format waives certain requirements of 37 CFR 1.121.

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